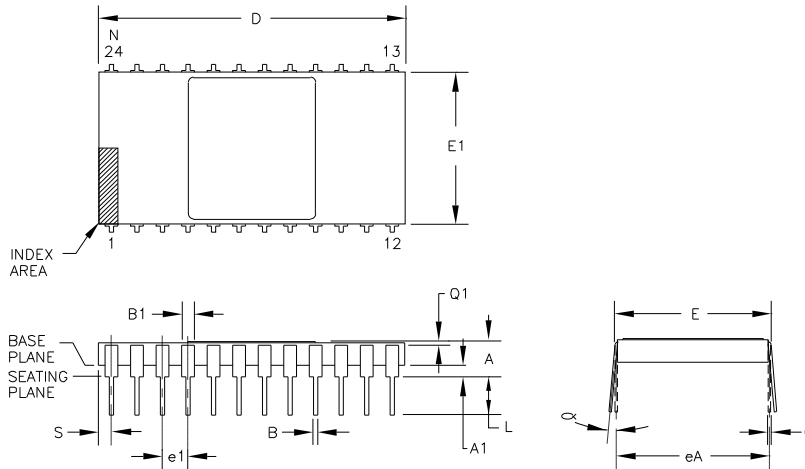


Package Number 165 - 24-Lead Side Braze DIP, .600 Wide



DIM	INCHES		MILLIMETERS		N	Q	E
	MIN.	MAX.	MIN.	MAX.			
A	.085	.190	2.16	4.83			
A1	.020	.070	0.51	1.78			
B	.015	.023	0.38	0.58	5		
B1	.038	.060	0.97	1.52	5		
C	.008	.012	0.20	0.30			
D	1.180	1.220	29.97	30.99			
E	.595	.625	15.11	15.88			
E1	.580	.610	14.73	15.49	6		
e1	.100	TYP.	2.54	TYP.	2		
eA	.600	TYP.	15.24	TYP.	2		
L	.125	.175	3.18	4.45			
N	24		24		4		
Q1	.010	--	0.25	--			
S	.030	.065	0.76	1.65			

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5-1973.
2. LEADS WITHIN .005 IN. (0.13mm) RADIUS OF TRUE POSITION (TP) AT GAUGE PLANE WITH MAXIMUM MATERIAL CONDITION AND UNIT INSTALLED.
3. α APPLIES TO SPREAD LEADS PRIOR TO INSTALLATION.
4. N IS THE NUMBER OF TERMINAL POSITIONS.

5. OUTLINES ON WHICH THE SEATING PLANE IS COINCIDENT WITH THE PLANE ($A1 = 0$), TERMINALS LEAD STANDOFFS ARE NOT REQUIRED, AND B1 MAY EQUAL B ALONG ANY PART OF THE LEAD ABOVE THE SEATING/BASE PLANE.
6. E1 DOES NOT INCLUDE PARTICLES OF PACKING MATERIALS.
7. CONTROLLING DIMENSION: INCH.
8. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.

PACKAGE NUMBER: ZZ165 REV.: C
 JEDEC NUMBER: MO-038-AA



PACKAGE DRAWING

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